

under 37 C.F.R. § 1.136(a), and any fees required therefor (including fees for net addition of claims) are hereby authorized to be charged to our Deposit Account No. 19-0036.

*Amendments*

*In the Claims:*

Please substitute the following claims 58, 62, 67, and 71 for the respective pending claims 58, 62, 67, and 71:

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58. (Amended) An electronic component comprising:

- a substrate including a conductive area;
- a passivation layer disposed on a surface of said substrate, said passivation layer having an opening at said conductive area of said substrate;
- at least one electrically conductive layer disposed on said passivation layer and on said conductive area of said substrate; and
- a resilient, conductive contract structure comprising a base portion electrically coupled through said at least one at least one electrically conductive layer to said conductive area of said substrate, a tip portion displaced away from said substrate and said conductive area, and a beam portion between said base portion and said tip portion, wherein:

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a length of said beam portion extends from said base portion to said tip portion,  
and  
a width of said beam portion decreases along said length from said base portion  
to said tip portion.

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E1

62. (Amended) The electronic component of claim 58, wherein said substrate comprises  
a semiconductor device.

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67. (Amended) An electronics system comprising:

- a first substrate including a conductive area;
- a passivation layer disposed on a surface of said first substrate, said passivation  
layer having an opening at said conductive area of said first substrate;
- at least one electrically conductive layer disposed on said passivation layer and  
on said conductive area of said first substrate; and
- a resilient conductive contact structure comprising a base portion electrically  
coupled through said at least one at least one electrically conductive layer to said  
conductive area of said first substrate, a tip portion displaced away from said first  
substrate, and a beam portion between said base portion and said tip portion, wherein a  
length of said beam portion extends from said base portion to said tip portion, and a  
width of said beam portion decreases along said length from said base portion to said tip  
portion; and
- a second substrate including a conductive contact element in physical contact  
with said contact structure and deflecting said contact structure, said contact structure

E1 ~~control~~  
exerting a force against said contact element due to said resiliency of said contact structure.

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71. (Amended) The electronics system of claim 67, wherein said first substrate comprises a semiconductive device.

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Please add the following new claims:

76. (New) The electronic component of claim 58, wherein said at least one electrically conductive layer includes:

a shorting layer; and

a conductive layer; said shorting layer being provided between said conductive layer and said surface of said substrate.

77. (New) The electronic component of claim 76, wherein said at least one electrically conductive layer further includes a seed layer provided between said conductive layer and said base portion of said resilient conductive contact structure.

78. (New) The electronics system of claim 67, wherein said at least one electrically conductive layer includes:

a shorting layer; and

a conductive layer; said shorting layer being provided between said conductive layer and said surface of said substrate.

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79. (New) The electronics system of claim 78, wherein said at least one electrically  
conductive layer further includes a seed layer provided between said conductive layer  
and said base portion of said resilient conductive contact structure.

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